CX3399999 | 125T135 EMPTY DUCT COEX



ConQuest® Empty Conduit, 1 1/4 in, SDR 13.5, terracotta

Product Classification	
Product Type	Empty conduit
Product Brand	ConQuest®
General Specifications	
Color	Terracotta
Conduit Type	Non-toneable
Density Test Method	ASTM D792A
Density, maximum	0.955 g/cm³ 0.035 lb/in³
Density, minimum	0.941 g/cm³ 0.034 lb/in³
Design Standard	ASTM D3350-05
Wall Type	Smooth
Dimensions	
Length	914.4 m 3000 ft
Inner Diameter, nominal	35.408 mm 1.394 in
Outer Diameter, nominal	42.164 mm 1.66 in
Wall Thickness Designation	SDR 13.5
Wall Thickness, minimum	3.124 mm 0.123 in
Nominal Size	1-1/4 in
Material Specifications	
Flexural Modulus, minimum	551.581 N/mm² 80000 psi
Flexural Property Test Method	ASTM D790
Hydrostatic Design Basis	Not pressure rated
Hydrostatic Design Test Method	ASTM D2837
Material Type	High density polyethylene (HDPE)
Melt Flow Rate Test Method	ASTM D1238

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Melt Flow Rate, maximum	1	0.39 g/10 min
Mechanical Spec	ifications	
Minimum Bend Radius, u	nsupported	457.2 mm 18 in
Tensile Property Test Me	thod	ASTM D638
Tensile Strength at yield, minimum		20.684 N/mm² 3000 psi
Pulling Tension, maximum		571.526 kg 1260 lb
Environmental Specifications		
Environmental Stress Crack Resistance		Failure rate of 10% within 96 hours
Environmental Stress Test Method		ASTM D1693, ESCR Condition B
Packaging and Weights		
Weight, net		394.363 kg/km 265 lb/kft
Regulatory Compliance/Certifications		
Agency	Classification	
ISO 9001:2015	Designed, manufactured and/or distributed under this quality management system	
* Footnotes		

Environmental Stress Crack Resistance ESCR-Environmental Stress Crack Resistence

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